MBR160 is a Preferred Device

Axial Lead Rectifiers

The MBR150/160 series employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlap contact. Ideally suited for use as rectifiers in low-voltage, high-frequency inverters, free wheeling diodes, and polarity protection diodes.

Features

- Low Reverse Current
- Low Stored Charge, Majority Carrier Conduction
- Low Power Loss/High Efficiency
- Highly Stable Oxide Passivated Junction
- These are Pb-Free Devices*

Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Cathode Indicated by Polarity Band

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	MBR150 MBR160	V _{RRM} V _{RWM} V _R	50 60	>
RMS Reverse Voltage	MBR150 MBR160	V _{R(RMS)}	35 42	V
		I _O	1.0	Α
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz, T _L = 70°C)		I _{FSM}	25 (for one cycle)	Α
Operating and Storage Junction Temperature Range (Reverse Voltage Applied)		T _J , T _{stg}	– 65 to +150	°C

THERMAL CHARACTERISTICS (Notes 1 and 2)

•	,		
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	Raja	80	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- Recommended Operating Conditions may affect device reliability.

 1. Lead Temperature reference is cathode lead 1/32" from case.
- 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIERS 1.0 AMPERE – 50 AND 60 VOLTS



MARKING DIAGRAM



A = Assembly Location

MBR1x0 = Device Code

x = 5 or 6

Y = Year
WW = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

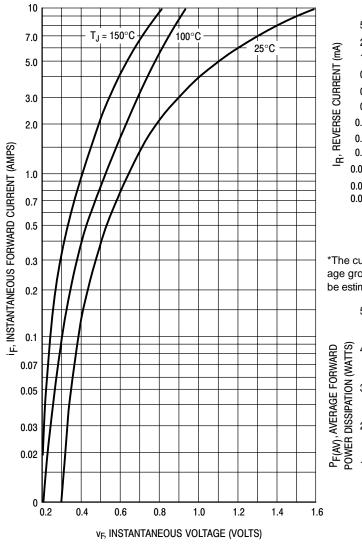
See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Preferred devices are recommended choices for future use and best overall value

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_L = 25°C unless otherwise noted) (Note 1)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(i_F=0.1 \text{ A}) \\ &(i_F=1.0 \text{ A}) \\ &(i_F=3.0 \text{ A}) \end{aligned} $	V _F	0.550 0.750 1.000	V
Maximum Instantaneous Reverse Current @ Rated dc Voltage (Note 2) $ (T_L = 25^{\circ}\text{C}) $ $ (T_L = 100^{\circ}\text{C}) $	İR	0.5 5.0	mA



10 T_{.I} = 150°C 5.0 125°C 2.0 1.0 100°C 0.5 0.2 75°C 0.1 0.05 0.02 0.01 0.005 $25^{\circ}C$ 0.002 0.001 0 10 30 40 50 60 70 V_R, REVERSE VOLTAGE (VOLTS)

Figure 2. Typical Reverse Current*

*The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if V_R is sufficiently below rated V_R .

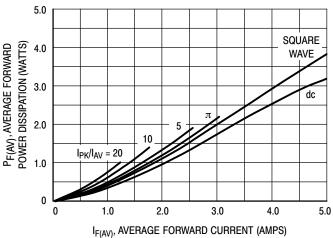


Figure 1. Typical Forward Voltage

Figure 3. Forward Power Dissipation

THERMAL CHARACTERISTICS

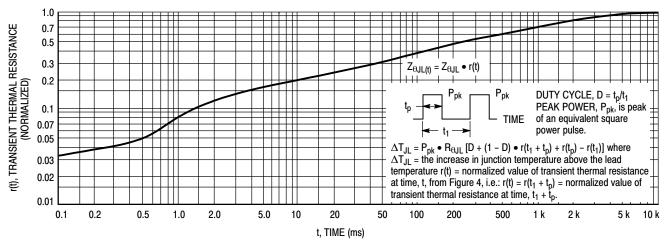


Figure 4. Thermal Response

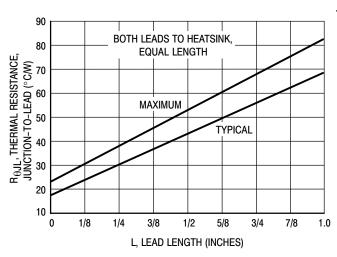


Figure 5. Steady-State Thermal Resistance

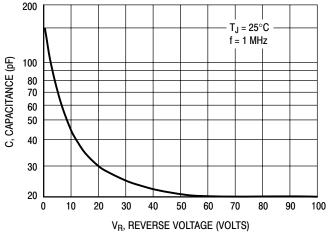


Figure 6. Typical Capacitance

NOTE 1. — MOUNTING DATA:

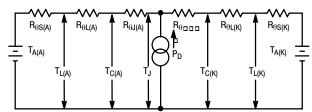
Data shown for thermal resistance junction—to—ambient $(R_{\theta JA})$ for the mounting shown is to be used as a typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

Typical Values for $R_{\theta JA}$ in Still Air

Mounting	Lead Length, L (in)				Б	
Method	1/8	1/4	1/2	3/4	$R_{\theta JA}$	
1	52	65	72	85	°C/W	
2	67	80	87	100	°C/W	
3	_		50		°C/W	

NOTE 2. — THERMAL CIRCUIT MODEL:

(For heat conduction through the leads)



Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. For a given total lead length, lowest values occur when one side of the rectifier is brought as close as possible to the heatsink. Terms in the model signify:

 $T_A =$ Ambient Temperature $T_C =$ Case Temperature

 $T_J = Junction Temperature$ $T_L = Lead Temperature$

 $R_{\theta S}$ = Thermal Resistance, Heatsink-to-Ambient

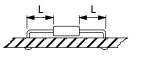
 $R_{\theta L}$ = Thermal Resistance, Lead-to-Heatsink $R_{\theta J}$ = Thermal Resistance, Junction-to-Case

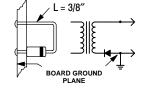
 P_D = Power Dissipation

Mounting Method 1 P.C. Board with 1–1/2" x 1–1/2" copper surface.

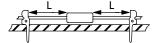
Mounting Method 3

P.C. Board with 1–1/2" x 1–1/2" copper surface.





Mounting Method 2



VECTOR PIN MOUNTING

(Subscripts A and K refer to anode and cathode sides, respectively.) Values for thermal resistance components are: $R_{\rm HI} = 100$ °C/W/in typically and 120°C/W/in maximum. $R_{\theta J} = 36^{\circ}\text{C/W}$ typically and 46°C/W maximum.

NOTE 3. — HIGH FREQUENCY OPERATION:

Since current flow in a Schottky rectifier is the result of majority carrier conduction, it is not subject to junction diode forward and reverse recovery transients due to minority carrier injection and stored charge. Satisfactory circuit analysis work may be performed by using a model consisting of an ideal diode in parallel with a variable capacitance. (See Figure 6)

Rectification efficiency measurements show that operation will be satisfactory up to several megahertz. For example, relative waveform rectification efficiency is approximately 70 percent at 2 MHz, e.g., the ratio of dc power to RMS power in the load is 0.28 at this frequency, whereas perfect rectification would yield 0.406 for sine wave inputs. However, in contrast to ordinary junction diodes, the loss in waveform efficiency is not indicative of power loss: it is simply a result of reverse current flow through the diode capacitance, which lowers the dc output voltage.

ORDERING INFORMATION

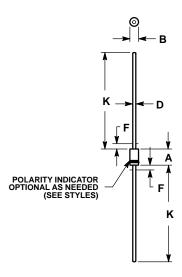
Device	Package	Shipping [†]
MBR150	Axial Lead*	1000 Units / Bag
MBR150G	Axial Lead*	1000 Units / Bag
MBR150RL	Axial Lead*	5000 / Tape & Reel
MBR150RLG	Axial Lead*	5000 / Tape & Reel
MBR160	Axial Lead*	1000 Units / Bag
MBR160G	Axial Lead*	1000 Units / Bag
MBR160RL	Axial Lead*	5000 / Tape & Reel
MBR160RLG	Axial Lead*	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}This package is inherently Pb-Free.

PACKAGE DIMENSIONS

AXIAL LEAD CASE 59-10 ISSUE U



- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY POLARITY DENOTED BY CATHODE BAND. LEAD DIAMETER NOT CONTROLLED WITHIN F

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.161	0.205	4.10	5.20
В	0.079	0.106	2.00	2.70
D	0.028	0.034	0.71	0.86
F		0.050		1.27
ĸ	1 000		25 40	

STYLE 1: PIN 1. CATHODE (POLARITY BAND)

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada

Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

ON Semiconductor:

MBR150 MBR150RL MBR160 MBR160RL